

**1 MEGABIT (131,072 x 8 BIT)
5 VOLT CMOS FLASH MEMORY**

Features

- 128Kx8-bit Organization
- Address Access Time: 90 ns
- Single 5V ± 10% Power Supply
- Sector Erase Mode Operation
- 512 bytes per Sector, 256 Sectors
 - Sector-Erase Cycle Time: 10ms (Max)
 - Byte-Program Cycle Time: 30µs (Max)
- Minimum 1,000 Erase-Program Cycles
- Low power dissipation
 - Active Read Current: 20mA (Typ)
 - Active Program Current: 30mA (Typ)
 - Standby Current: 100µA (Max)
- Low V_{CC} Program Inhibit Below 3.2V
- Self-timed program/erase operations
- CMOS and TTL Interface
- Packages:
 - 32-pin Plastic DIP
 - 32-pin PLCC

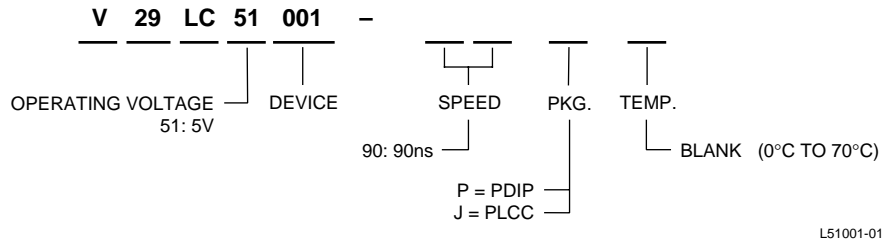
Description

The V29LC51001 is a high speed 131,072 x 8 bit CMOS flash memory. Programming or erasing the device is done with a single 5 Volt power supply. The device has separate chip enable \overline{CE} , program enable \overline{WE} , and output enable \overline{OE} controls to eliminate bus contention.

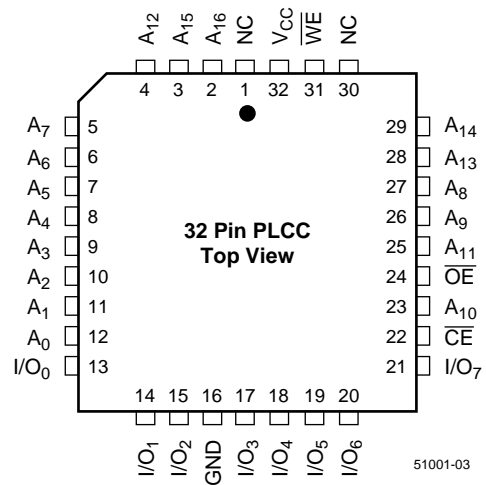
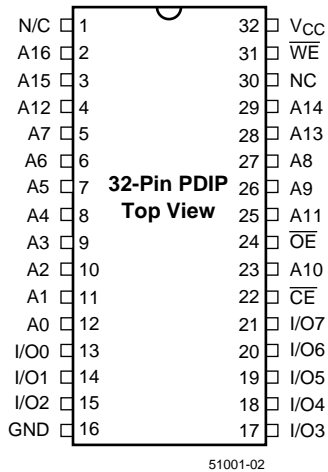
The V29LC51001 features a sector erase operation which allows each sector to be erased and reprogrammed without affecting data stored in other sectors. The device also supports full chip erase.

Device Usage Chart

Operating Temperature Range	Package Outline		Access Time (ns)	Temperature Mark
	P	J	90	
0°C to 70°C	•	•	•	Blank



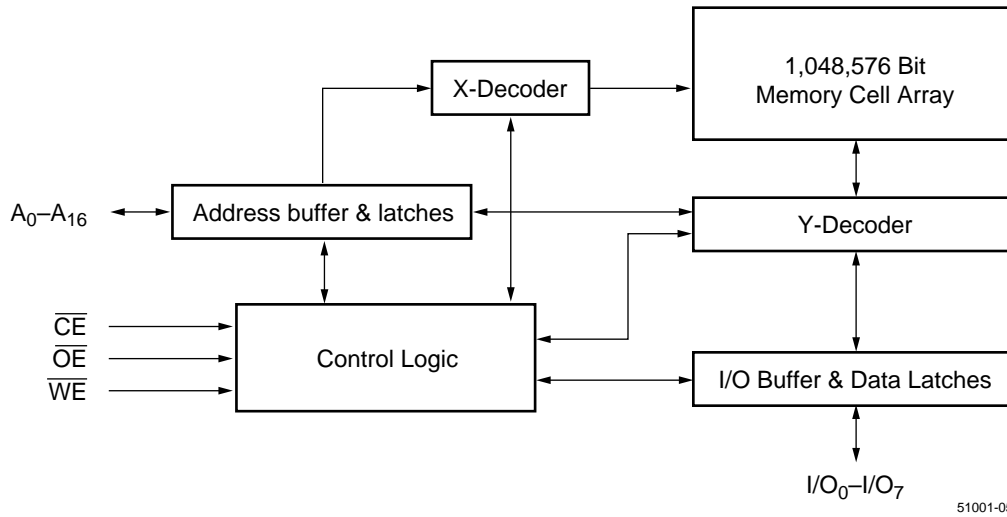
Pin Configurations



Pin Names

A ₀ -A ₁₆	Address Inputs
I/O ₀ -I/O ₇	Data Input/Output
CE	Chip Enable
OE	Output Enable
WE	Program Enable
V _{CC}	5V ± 10% Power Supply
GND	Ground
NC	No Connect

Functional Block Diagram



Capacitance (1,2)

Symbol	Parameter	Test mSetup	Typ.	Max.	Units
C _{IN}	Input Capacitance	V _{IN} = 0	6	8	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0	8	12	pF
C _{IN2}	Control Pin Capacitance	V _{IN} = 0	8	10	pF

NOTE:

1. Capacitance is sampled and not 100% tested.
2. T_A = 25°C, V_{CC} = 5V ± 10%, f = 1 MHz.

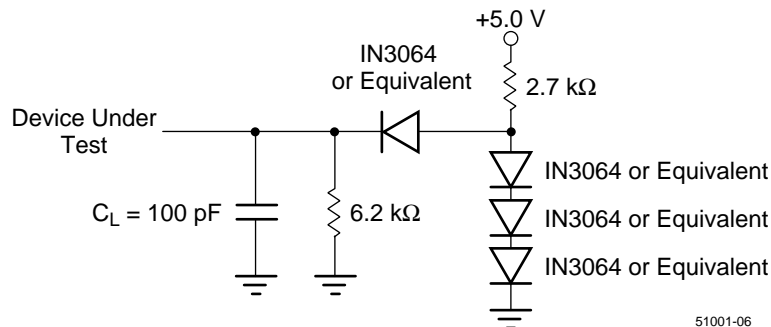
Latch Up Characteristics(1)

Parameter	Min.	Max.	Unit
Input Voltage with Respect to GND on A ₉ , \overline{OE}	-1	+13	V
Input Voltage with Respect to GND on I/O, address or control pins	-1	V _{CC} + 1	V
V _{CC} Current	-100	+100	mA

NOTE:

1. Includes all pins except V_{CC}. Test conditions: V_{CC} = 5V, one pin at a time.

AC Test Load



Absolute Maximum Ratings⁽¹⁾

Symbol	Parameter	Commercial	Unit
V_{IN}	Input Voltage (input or I/O pins)	-2 to +7	V
V_{IN}	Input Voltage (A_9 pin, \overline{OE})	-2 to +13	V
V_{CC}	Power Supply Voltage	-0.5 to +5.5	V
T_{STG}	Storage Temperature (Plastic)	-65 to +125	°C
T_{OPR}	Operating Temperature	0 to +70	°C
I_{OUT}	Short Circuit Current ⁽²⁾	200 (Max.)	mA

NOTE:

1. Stress greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. No more than one output maybe shorted at a time and not exceeding one second long.

DC Electrical Characteristics

(over the commercial operating range)

Parameter Name	Parameter	Test Conditions	Min.	Max.	Unit
V_{IL}	Input LOW Voltage	$V_{CC} = V_{CC} \text{ Min.}$	—	0.8	V
V_{IH}	Input HIGH Voltage	$V_{CC} = V_{CC} \text{ Max.}$	2	—	V
I_{IL}	Input Leakage Current	$V_{IN} = \text{GND to } V_{CC}, V_{CC} = V_{CC} \text{ Max.}$	—	± 1	μA
I_{OL}	Output Leakage Current	$V_{OUT} = \text{GND to } V_{CC}, V_{CC} = V_{CC} \text{ Max.}$	—	± 10	μA
V_{OL}	Output LOW Voltage	$V_{CC} = V_{CC} \text{ Min.}, I_{OL} = 2.1 \text{ mA}$	—	0.4	V
V_{OH}	Output HIGH Voltage	$V_{CC} = V_{CC} \text{ Min.}, I_{OH} = -400 \mu\text{A}$	2.4	—	V
I_{CC1}	Read Current	$\overline{CE} = \overline{OE} = V_{IL}, \overline{WE} = V_{IH}, \text{ all I/Os open, Address input} = V_{IL}/V_{IH}, \text{ at } f = 1/t_{RC} \text{ Min.}, V_{CC} = V_{CC} \text{ Max.}$	—	40	mA
I_{CC2}	Program Current	$\overline{CE} = \overline{WE} = V_{IL}, \overline{OE} = V_{IH}, V_{CC} = V_{CC} \text{ Max.}$	—	50	mA
I_{SB}	TTL Standby Current	$\overline{CE} = \overline{OE} = \overline{WE} = V_{IH}, V_{CC} = V_{CC} \text{ Max.}$	—	2	mA
I_{SB1}	CMOS Standby Current	$\overline{CE} = \overline{OE} = \overline{WE} = V_{CC} - 0.3 \text{ V}, V_{CC} = V_{CC} \text{ Max.}$	—	100	μA
V_H	Device ID Voltage for A_9	$\overline{CE} = \overline{OE} = V_{IL}, \overline{WE} = V_{IH}$	11.5	12.5	V
I_H	Device ID Current for A_9	$\overline{CE} = \overline{OE} = V_{IL}, \overline{WE} = V_{IH}, A_9 = V_H \text{ Max.}$	—	50	μA

AC Electrical Characteristics

(over all temperature ranges)

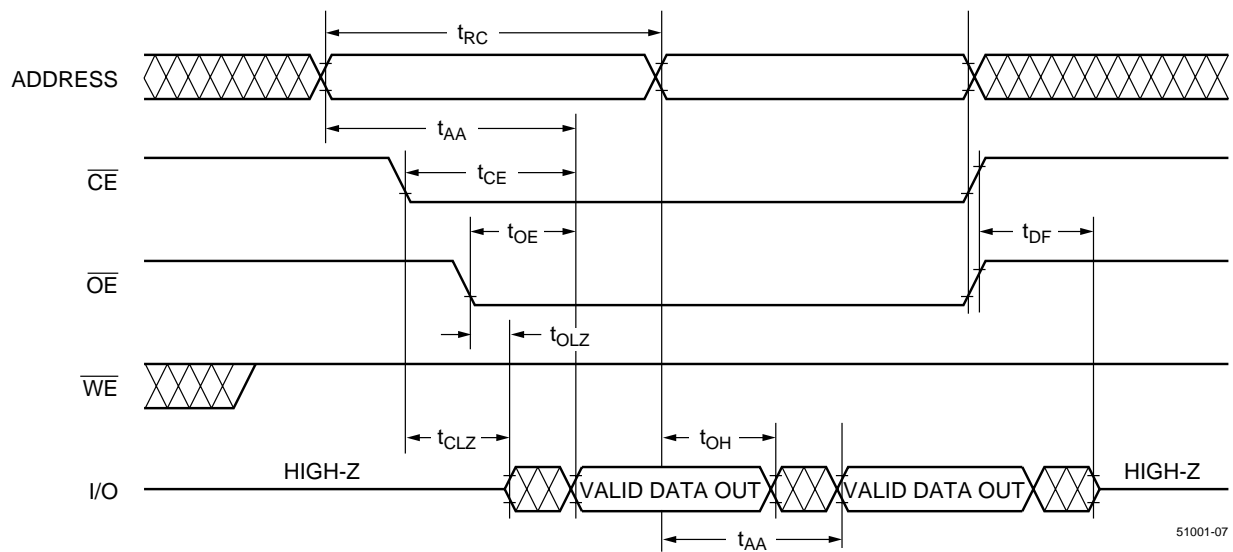
Read Cycle

Parameter Name	Parameter	-90		Unit
		Min.	Max.	
t_{RC}	Read Cycle Time	90	—	ns
t_{AA}	Address Access Time	—	90	ns
t_{ACS}	Chip Enable Access Time	—	90	ns
t_{OE}	Output Enable Access Time	—	40	ns
t_{CLZ}	\overline{CE} Low to Output Active	0	—	ns
t_{OLZ}	\overline{OE} Low to Output Active	0	—	ns
t_{DF}	Output Enable or Chip Disable to Output in High Z	0	20	ns
t_{OH}	Output Hold from Address Change	0	—	ns

Program (Erase/Program) Cycle

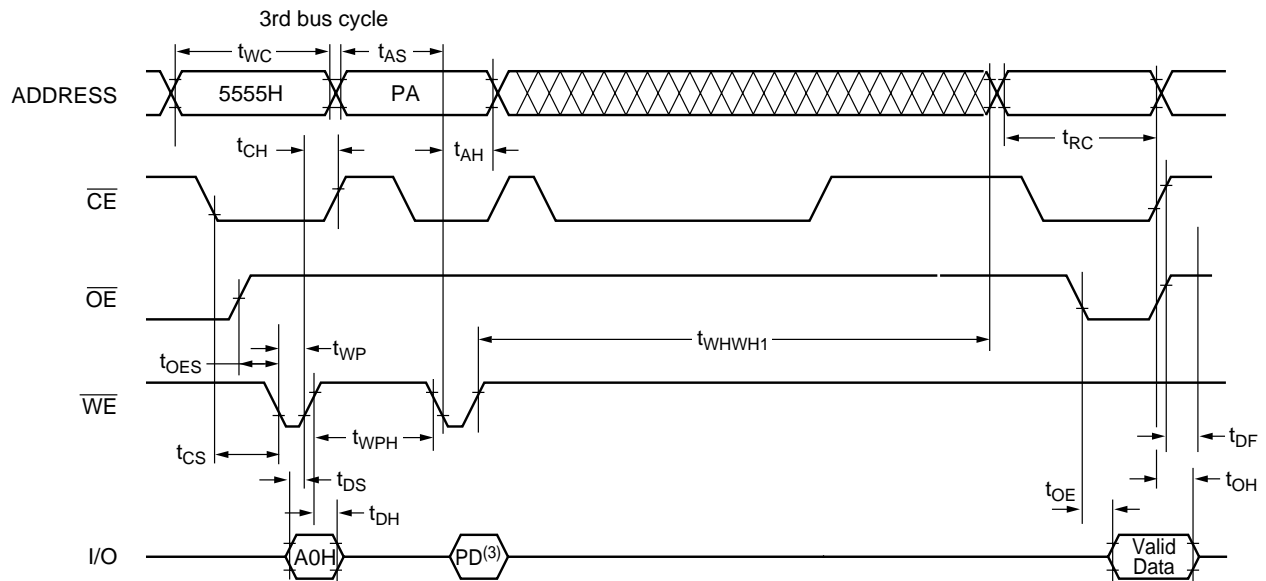
Parameter Name	Parameter	-90			Unit
		Min.	Typ.	Max.	
t_{WC}	Program Cycle Time	90	—	—	ns
t_{AS}	Address Setup Time	0	—	—	ns
t_{AH}	Address Hold Time	45	—	—	ns
t_{CS}	\overline{CE} Setup Time	0	—	—	ns
t_{CH}	\overline{CE} Hold Time	0	—	—	ns
t_{OES}	\overline{OE} Setup Time	0	—	—	ns
t_{OEH}	\overline{OE} High Hold Time	0	—	—	ns
t_{WP}	\overline{WE} Pulse Width	45	—	—	ns
t_{WPH}	\overline{WE} Pulse Width High	35	—	—	ns
t_{DS}	Data Setup Time	30	—	—	ns
t_{DH}	Data Hold Time	0	—	—	ns
t_{WHWH1}	Programming Cycle	—	—	30	μ s
t_{WHWH2}	Sector Erase Cycle	—	—	10	ms
t_{WHWH3}	Chip Erase Cycle	—	2	—	sec

Waveforms of Read Cycle



51001-07

Waveforms of \overline{WE} Controlled-Program Cycle

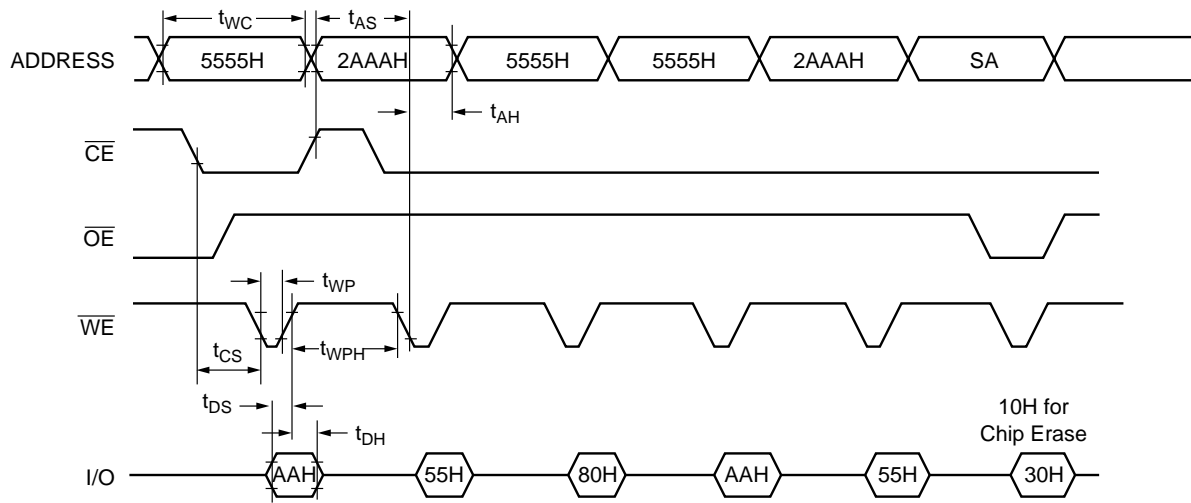


51001-08

NOTES:

1. PA: The address of the memory location to be programmed.
2. PD: The data at the byte address to be programmed.

Waveforms of Erase Cycle⁽¹⁾



51001-10

NOTES:

1. PA: The address of the memory location to be programmed.
2. PD: The data at the byte address to be programmed.
3. SA: The sector address for Sector Erase. Address = don't care for Chip Erase.

FUNCTIONAL DESCRIPTION

Read Cycle

A read cycle is performed by holding both \overline{CE} and \overline{OE} signals LOW. Data Out becomes valid only when these conditions are met. During a read cycle \overline{WE} must be HIGH prior to \overline{CE} and \overline{OE} going LOW. \overline{WE} must remain HIGH during the read operation for the read to complete (see Table 1).

Output Disable

Returning \overline{OE} or \overline{CE} HIGH, whichever occurs first will terminate the read operation and place the I/O pins in the HIGH-Z state.

Standby

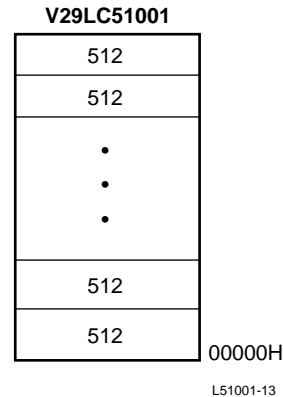
The device will enter standby mode when the \overline{CE} signal is HIGH. The I/O pins are placed in the HIGH-Z, independent of the \overline{OE} signal.

Command Sequence

The V29LC51001 does not provide the “reset” feature to return the chip to its normal state when an incomplete command sequence or an interruption has happened. In this case, normal operation (Read Mode) can be restored by issuing a “non-existent” command sequence, for example Address: 5555H, Data FFH.

Byte Program Cycle

The V29LC51001 is programmed on a byte-by-byte basis. The byte program operation is initiated by using a specific four-bus-cycle sequence: two unlock program cycles, a program setup command and program data program cycles (see Table 2).



During the byte program cycle, addresses are latched on the falling edge of either \overline{CE} or \overline{WE} , whichever is last. Data is latched on the rising edge of \overline{CE} or \overline{WE} , whichever is first. The byte program cycle can be \overline{CE} controlled or \overline{WE} controlled.

Sector Erase Cycle

The V29LC51001 features a sector erase operation which allows each sector to be erased and reprogrammed without affecting data stored in other sectors. Sector erase operation is initiated by using a specific six-bus-cycle sequence: Two unlock program cycles, a setup command, two additional unlock program cycles, and the sector erase command (see Table 2). A sector must be first erased before it can be reprogrammed. While in the internal erase mode, the device ignores any program attempt into the device. Sector erase is completed in 10ms max. The V29LC51001 is shipped with pre-erased sectors (all bits = 1).

Table 1. Operation Modes Decoding

Decoding Mode	\overline{CE}	\overline{OE}	\overline{WE}	A ₀	A ₁	A ₉	I/O
Read	V _{IL}	V _{IL}	V _{IH}	A ₀	A ₁	A ₉	READ
Byte Write	V _{IL}	V _{IH}	V _{IL}	A ₀	A ₁	A ₉	PD
Standby	V _{IH}	X	X	X	X	X	HIGH-Z
Output Disable	V _{IL}	V _{IH}	V _{IH}	X	X	X	HIGH-Z

NOTES:

1. X = Don't Care, V_{IH} = HIGH, V_{IL} = LOW. V_H = 12.5V Max.
2. PD: The data at the byte address to be programmed.

Table 2. Command Codes

Command Sequence	First Bus Program Cycle		Second Bus Program Cycle		Third Bus Program Cycle		Fourth Bus Program Cycle		Fifth Bus Program Cycle		Six Bus Program Cycle	
	Address	Data	Address	Data	Address	Data	Address	Data	Address	Data	Address	Data
Read	XXXXH	F0H										
Read	5555H	AAH	2AAAH	55H	5555H	F0H	RA	RD				
Autoselect	5555H	AAH	2AAAH	55H	5555H	90H	00H	40H(3)				
							01H	60H(4)				
Byte Program	5555H	AAH	2AAAH	55H	5555H	A0H	PA	PD(2)				
Chip Erase	5555H	AAH	2AAAH	55H	5555H	80H	5555H	AAH	2AAAH	55H	5555H	10H
Sector Erase	5555H	AAH	2AAAH	55H	5555H	80H	5555H	AAH	2AAAH	55H	PA(1)	30H

NOTES:

1. PA: The address of the memory location to be programmed.
2. PD: The data at the byte address to be programmed.
3. 40H: Manufacturing ID
4. 60H: Device ID

Chip Erase Cycle

The V29LC51001 features a chip-erase operation. The chip erase operation is initiated by using a specific six-bus-cycle sequence: two unlock program cycles, a setup command, two additional unlock program cycles, and the chip erase command (see Table 2).

The chip erase operation is performed sequentially, one sector at a time. When the automated on chip erase algorithm is requested with the chip erase command sequence, the device automatically programs and verifies the entire memory array for an all zero pattern prior to erasure

The automatic erase begins on the rising edge of the last \overline{WE} or \overline{CE} pulse in the command sequence and terminates 500ms later.

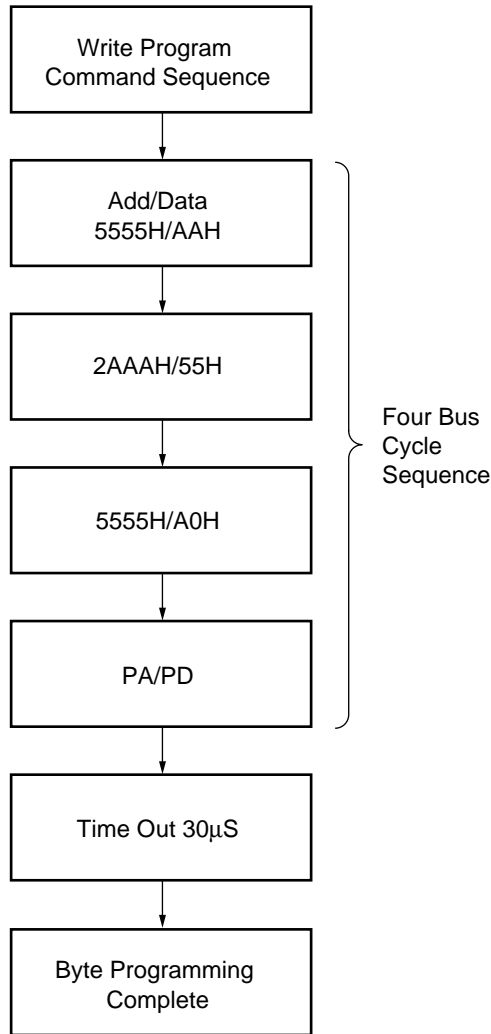
Hardware Data Protection

V_{CC} Sense Protection: the program operation is inhibited when VCC is less than 2.5V.

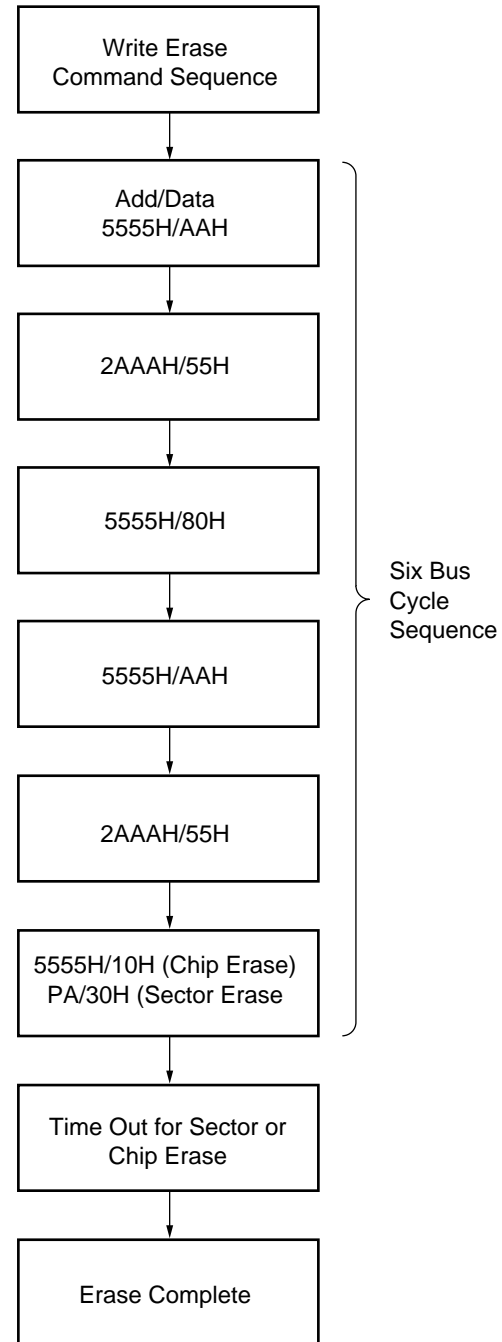
Noise Protection: a CE or WE pulse of less than 5ns will not initiate a program cycle.

Program Inhibit Protection: holding any one of OE LOW, CE HIGH or WE HIGH inhibits a program cycle.

Byte Program Algorithm



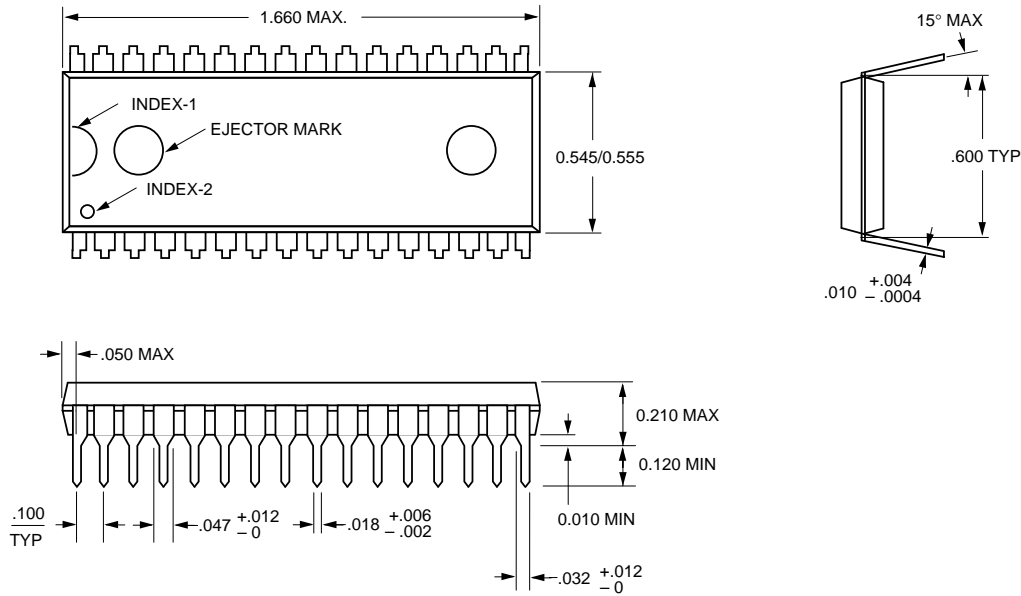
Chip/Sector Erase Algorithm



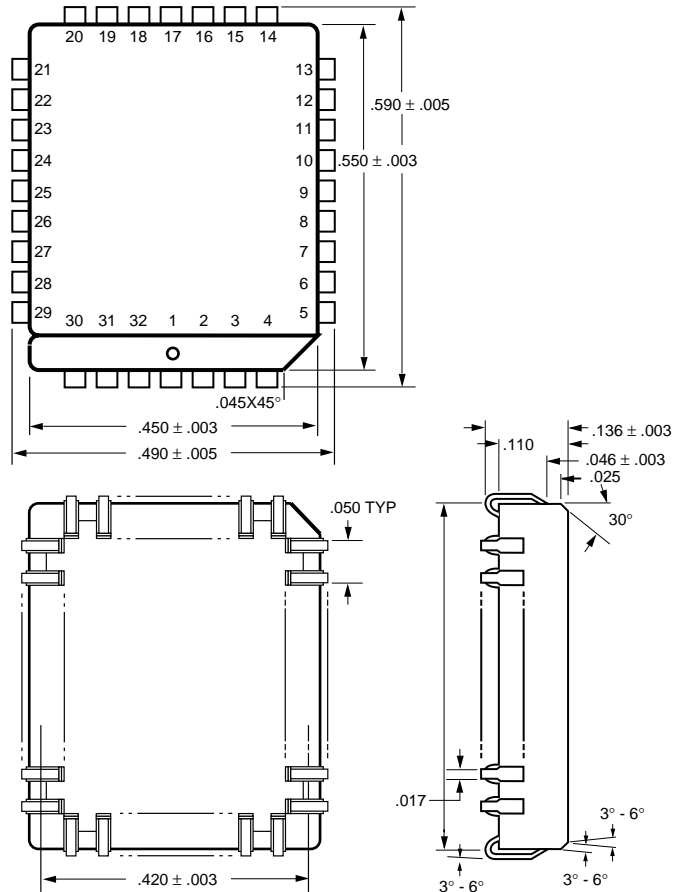
L51001-14

Package Diagrams

32-pin Plastic DIP



32-pin PLCC



U.S.A.

3910 NORTH FIRST STREET
SAN JOSE, CA 95134
PHONE: 408-433-6000
FAX: 408-433-0952

HONG KONG

19 DAI FU STREET
TAIPO INDUSTRIAL ESTATE
TAIPO, NT, HONG KONG
PHONE: 852-2666-3307
FAX: 852-2770-8011

TAIWAN

7F, NO. 102
MIN-CHUAN E. ROAD, SEC. 3
TAIPEI
PHONE: 886-2-2545-1213
FAX: 886-2-2545-1209

NO 19 LI HSIN ROAD
SCIENCE BASED IND. PARK
HSIN CHU, TAIWAN, R.O.C.
PHONE: 886-3-579-5888
FAX: 886-3-566-5888

SINGAPORE

10 ANSON ROAD #23-13
INTERNATIONAL PLAZA
SINGAPORE 079903
PHONE: 65-3231801
FAX: 65-3237013

JAPAN

ONZE 1852 BUILDING 6F
2-14-6 SHINTOMI, CHUO-KU
TOKYO 104-0041
PHONE: 03-3537-1400
FAX: 03-3537-1402

UK & IRELAND

SUITE 50, GROVEWOOD
BUSINESS CENTRE
STRATHCLYDE BUSINESS
PARK
BELLSHILL, LANARKSHIRE,
SCOTLAND, ML4 3NQ
PHONE: 44-1698-748515
FAX: 44-1698-748516

**GERMANY
(CONTINENTAL
EUROPE & ISRAEL)**

BENZSTRASSE 32
71083 HERRENBERG
GERMANY
PHONE: +49 7032 2796-0
FAX: +49 7032 2796 22

U.S. SALES OFFICES**NORTHWESTERN**

3910 NORTH FIRST STREET
SAN JOSE, CA 95134
PHONE: 408-433-6000
FAX: 408-433-0952

SOUTHWESTERN

302 N. EL CAMINO REAL #200
SAN CLEMENTE, CA 92672
PHONE: 949-361-7873
FAX: 949-361-7807

**CENTRAL,
NORTHEASTERN &
SOUTHEASTERN**

604 FIELDWOOD CIRCLE
RICHARDSON, TX 75081
PHONE: 972-690-1402
FAX: 972-690-0341

The information in this document is subject to change without notice.

MOSEL VITELIC makes no commitment to update or keep current the information contained in this document. No part of this document may be copied or reproduced in any form or by any means without the prior written consent of MOSEL-VITELIC.

MOSEL VITELIC subjects its products to normal quality control sampling techniques which are intended to provide an assurance of high quality products suitable for usual commercial applications. MOSEL VITELIC does not do testing appropriate to provide 100% product quality assurance and does not assume any liability for consequential or incidental arising from any use of its products. If such products are to be used in applications in which personal injury might occur from failure, purchaser must do its own quality assurance testing appropriate to such applications.